IEEE P802.11  
Wireless LANs

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| TGbe 2020 September to November teleconference minutes | | | | |
| Date: 2020-09-16 | | | | |
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Abstract

This document contains the minutes for September to November 2020 TGbe teleconferences.

Revisions:

* Rev0: First revision of the document. Added minutes for joint meeting call the 15th of September.

# Tuesday 15 September 2020, 19:00 – 21:00 ET

**Introduction**

1. The Chair, Alfred Asterjadhi (Qualcomm), calls the meeting to order at 19:02 ET. The Chair notifies that the agenda is in 1269r5.
2. IEEE 802 and 802.11 IPR policy and procedure. If anyone in this meeting is personally aware of the holder of any patent claims that are potentially essential to implementation of the proposed standard(s) under consideration by this group please speak up now. Nobody speaks/writes up.
   * The Chair goes throughPatent And Procedures.
3. Attendance reminder.
   1. Participation slide: <https://mentor.ieee.org/802-ec/dcn/16/ec-16-0180-05-00EC-ieee-802-participation-slide.pptx>
   2. Please record your attendance during the conference call by using the IMAT system:
      * 1) login to [imat](https://imat.ieee.org/attendance), 2) select “802.11 Telecons (<Month>)” entry, 3) select “C/LM/WG802.11 Attendance” entry, 4) click “TGbe <MAC/PHY/Joint> conference call that you are attending.
   3. If you are unable to record the attendance via [IMAT](https://imat.ieee.org/attendance) then please send an e-mail to Dennis Sundman ([dennis.sundman@ericsson.com](mailto:dennis.sundman@ericsson.com)) and Alfred Asterjadhi ([aasterja@qti.qualcomm.com](mailto:aasterja@qti.qualcomm.com))
   4. Please ensure that the following information is listed correctly when joining the call:
      * "[voter status] First Name Last Name (Affiliation)"
   5. Participants reported in IMAT:

* Abdelaal, Rana Broadcom Corporation
* Abouelseoud, Mohamed Sony Corporation
* Aboulmagd, Osama Huawei Technologies Co.,  Ltd
* Adachi, Tomoko TOSHIBA Corporation
* Agarwal, Peyush Broadcom Corporation
* Akhmetov, Dmitry Intel Corporation
* Aldana, Carlos Facebook
* An, Song-Haur INDEPENDENT
* Andersdotter, Amelia None - Self-funded
* Ansley, Carol IEEE member / Self Employed
* Anwyl, Gary MediaTek Inc.
* Asterjadhi, Alfred Qualcomm Incorporated
* Au, Kwok Shum Huawei Technologies Co.,  Ltd
* Au, Oscar Origin Wireless
* B, Hari Ram NXP Semiconductors
* Baek, SunHee LG ELECTRONICS
* Baik, Eugene Qualcomm Incorporated
* baron, stephane Canon Research Centre France
* Bei, Jianwei NXP Semiconductors
* Berkema, Alan HP Inc.
* Boldy, David Broadcom Corporation
* Cao, Rui NXP Semiconductors
* Cariou, Laurent Intel Corporation
* Carney, William Sony Corporation
* Chen, Canfeng Xiaomi Inc.
* Chen, Cheng Intel Corporation
* Chen, Cheng-Ming Qualcomm Incorporated
* Chen, Na MaxLinear Corp
* Cheng, Paul MediaTek Inc.
* Choo, Seungho Senscomm Semiconductor Co., Ltd.
* Chu, Liwen NXP Semiconductors
* CHUN, JINYOUNG LG ELECTRONICS
* Chung, Chulho SAMSUNG
* Coffey, John Realtek Semiconductor Corp.
* Das, Dibakar Intel Corporation
* Das, Subir Perspecta Labs Inc.
* Derham, Thomas Broadcom Corporation
* de Vegt, Rolf Qualcomm Incorporated
* Ding, Baokun Huawei Technologies Co., Ltd
* Ding, Yanyi Panasonic Corporation
* DOAN, DUNG Qualcomm Incorporated
* Dong, Xiandong Xiaomi Inc.
* ElSherif, Ahmed Qualcomm Incorporated
* Erceg, Vinko Broadcom Corporation
* Fang, Yonggang ZTE TX Inc
* feng, Shuling MediaTek Inc.
* Fischer, Matthew Broadcom Corporation
* Gan, Ming Huawei Technologies Co., Ltd
* Ghaderipoor, Alireza MediaTek Inc.
* Ghosh, Chittabrata Intel Corporation
* Gong, Bo Huawei Technologies Co. Ltd
* Grandhe, Niranjan NXP Semiconductors
* Guo, Yuchen Huawei Technologies Co., Ltd
* Haider, Muhammad Kumail Facebook
* Hamilton, Mark Ruckus/CommScope
* Han, Zhiqiang ZTE Corporation
* Ho, Duncan Qualcomm Incorporated
* Hong, Hanseul WILUS Inc.
* Hsiao, Ching-Wen MediaTek Inc.
* Hsieh, Hung-Tao MediaTek Inc.
* Hsu, Chien-Fang MediaTek Inc.
* Hu, Chunyu Facebook
* Hu, Mengshi HUAWEI
* Huang, Guogang  Huawei
* Huang, Po-Kai Intel Corporation
* Hwang, Sung Hyun Electronics and Telecommunications Research Institute (ETRI)
* Inoue, Yasuhiko Nippon Telegraph and Telephone Corporation (NTT)
* Jang, Insun LG ELECTRONICS
* Jeon, Eunsung SAMSUNG ELECTRONICS
* Ji, Chenhe Huawei Technologies Co. Ltd
* Jiang, Jeng-Shiann Vertexcom Technologies
* Jiang, Jinjing Apple, Inc.
* Jones, Allan Activision
* JUNG, MYUNG CHEUL Pantech Inc.
* Kadampot, Ishaque Ashar Qualcomm Incorporated
* Kain, Carl USDoT
* Kakani, Naveen Qualcomm Incorporated
* Kamel, Mahmoud InterDigital, Inc.
* Kandala, Srinivas SAMSUNG
* Kang, Sugbong Apple, Inc.
* Kedem, Oren Huawei Technologies Co. Ltd
* Khan, Naseem Leidos Engineering. LLC
* Kim, Jeongki LG ELECTRONICS
* Kim, Myeong-Jin SAMSUNG
* kim, namyeong LG ELECTRONICS
* Kim, Sang Gook LG ELECTRONICS
* Kim, Sanghyun WILUS Inc
* Kim, Yongho Korea National University of Transportation
* Kim, Youhan Qualcomm Incorporated
* Kishida, Akira Nippon Telegraph and Telephone Corporation (NTT)
* Klein, Arik Huawei Technologies Co. Ltd
* Kneckt, Jarkko Apple, Inc.
* Ko, Geonjung WILUS Inc.
* Kondo, Yoshihisa Advanced Telecommunications Research Institute International (ATR)
* Kwon, Young Hoon NXP Semiconductors
* Lan, Zhou Broadcom Corporation
* Lee, Il-Gu Sungshin University
* Lee, Wookbong SAMSUNG
* Levitsky, Ilya IITP RAS
* Levy, Joseph InterDigital, Inc.
* Li, Jialing Qualcomm Incorporated
* Li, Nan ZTE Corporation
* Li, Qinghua Intel Corporation
* Li, Yiqing Huawei Technologies Co. Ltd
* Li, Yunbo Huawei Technologies Co., Ltd
* Lim, Dong Guk LG ELECTRONICS
* Lin, Wei Huawei Technologies Co. Ltd
* Lindskog, Erik SAMSUNG
* Liu, Der-Zheng Realtek Semiconductor Corp.
* Liu, Jianhan MediaTek Inc.
* Lou, Hanqing InterDigital, Inc.
* Lu, Liuming ZTE Corporation
* Luo, Chaoming Beijing OPPO telecommunications corp., ltd.
* Ma, Li MediaTek Inc.
* Ma, Mengyao HUAWEI
* Mehrnoush, Morteza Facebook
* Memisoglu, Ebubekir Istanbul Medipol University; Vestel
* Merlin, Simone Qualcomm Incorporated
* Minotani, Jun Panasonic Corporation
* Mirfakhraei, Khashayar Cisco Systems, Inc.
* Monajemi, Pooya Cisco Systems, Inc.
* Montreuil, Leo Broadcom Corporation
* Moon, Juseong Korea National University of Transportation
* Murti, Wisnu SeoulTech
* Nakano, Takayuki Panasonic Corporation
* Nam, Junyoung Qualcomm Incorporated
* Naribole, Sharan SAMSUNG
* Nezou, Patrice Canon Research Centre France
* Okada, Hiraku Nagoya University
* Ouchi, Masatomo Canon
* Pare, Thomas MediaTek Inc.
* Park, Eunsung LG ELECTRONICS
* Park, Minyoung Intel Corporation
* Patil, Abhishek Qualcomm Incorporated
* Patwardhan, Gaurav Hewlett Packard Enterprise
* Perkins, Richard Qorvo
* Petrick, Albert InterDigital, Inc.
* Pirhonen, Riku NXP Semiconductors
* porat, ron Broadcom Corporation
* Puducheri, Srinath Broadcom Corporation
* QIU, WEI Huawei Technologies Co., Ltd
* Rai, Kapil Qualcomm Incorporated
* Raissinia, Alireza Qualcomm Incorporated
* Rantala, Enrico-Henrik Nokia
* Redlich, Oded HUAWEI
* Rege, Kiran Perspecta Labs
* Rezk, Meriam Qualcomm Incorporated
* Rosdahl, Jon Qualcomm Technologies, Inc.
* Schelstraete, Sigurd Quantenna Communications, Inc.
* Shellhammer, Stephen Qualcomm Incorporated
* Sherlock, Ian Texas Instruments Incorporated
* Shilo, Shimi HUAWEI
* Smely, Di Dieter Kapsch TrafficCom AG
* Solaija, Muhammad Sohaib Istanbul Medipol University; Vestel
* Srinivasan, Shree Raman Qualcomm Incorporated
* Stott, Noel Keysight Technologies
* Strauch, Paul Qualcomm Incorporated
* Su, Hang Broadcom Corporation
* SUH, JUNG HOON Huawei Technologies Co. Ltd
* Sun, Bo ZTE Corporation
* Sun, Li-Hsiang InterDigital, Inc.
* Sun, Yanjun Qualcomm Incorporated
* Sundman, Dennis Ericsson AB
* SURACI, FRANK U.S. Department of Homeland Security
* Tian, Bin Qualcomm Incorporated
* Tian, Tao Unisoc Comm.
* Torab Jahromi, Payam Facebook
* Tsodik, Genadiy Huawei Technologies Co. Ltd
* Urabe, Yoshio Panasonic Corporation
* Varshney, Prabodh Nokia
* Vermani, Sameer Qualcomm Incorporated
* VIGER, Pascal Canon Research Centre France
* Wang, Hao Tencent
* Wang, Huizhao Quantenna Communications, Inc.
* Wang, Lei Huawei R&D USA
* Wang, Qi Apple, Inc.
* Wang, Xiaofei InterDigital, Inc.
* Ward, Lisa Rohde & Schwarz
* Wu, Kanke Qualcomm Incorporated
* Wu, Tianyu Apple, Inc.
* Wullert, John Perspecta Labs
* Xin, Liangxiao Sony Corporation
* Xin, Yan Huawei Technologies Co., Ltd
* Xue, Qi Qualcomm Incorporated
* Xue, Ruifeng Cisco Systems, Inc.
* Yan, Aiguo Oppo
* Yang, Jay Nokia
* YANG, RUI InterDigital, Inc.
* Yang, Steve TS MediaTek Inc.
* Yang, Yunsong Futurewei Technologies
* Yano, Kazuto Advanced Telecommunications Research Institute International (ATR)
* Yee, James MediaTek Inc.
* yi, yongjiang Futurewei Technologies
* Yona, Yair Qualcomm Incorporated
* Young, Christopher Broadcom Corporation
* Yu, Heejung Korea University
* Yu, Jian Huawei Technologies Co., Ltd
* Yu, Mao NXP Semiconductors
* Yukawa, Mitsuyoshi Canon, Inc.
* Zeng, Ruochen NXP Semiconductors
* Zeng, Yan Huawei Technologies Co.,  Ltd
* ZHANG, JIAYIN HUAWEI
* Zhang, Yan NXP Semiconductors
* Zou, Tristan Qualcomm Incorporated
* Zuo, Xin Tencent

1. Announcements: No particular announcements.
2. Call for nominations of TGbe officers
   1. Vicechairs and Secretary. The Chair mentiones that all current officers are willing to continue their service. If other people are interested, they shall speak up before the plenary.
3. Towards TGbe D0.1 Draft**–Status and Updates (Edward)**

* Alfred goes through an overview of the PDT status updates. We need to finalize the document by September 30.

Discussion:

C: I prefer that we take what we have by the end of this week.

* Edward goes through spec text and volunteers document.
* SP: Do you support having “MLO-TID mapping/Link” as Basics R1?
  + Y/N/A: 79/44/27 🡪 SP fails.

1. **Technical Submissions-Trigger**
   * [**764r2**](https://mentor.ieee.org/802.11/dcn/20/11-20-0764-02-00be-trigger-consideration.pptx)**, “Trigger Consideration”, Liwen Chu (NXP)**

**Summary:** The authors look at different extensions to the trigger frame design for EHT. They consider 2 options. The first option is based on reusing the .11ax frame structures, whereas the second option is to define new trigger types.

C: Slide 6, I think it’s better not to use the reserved bit.

C: Slide 4, you use user info. It has information which is not in the common part right?

A: Yes.

C: You could consider using another reserved bit to signal that this is an enhanced trigger frame.

* + [**828r1**](https://mentor.ieee.org/802.11/dcn/20/11-20-0828-01-00be-ru-allocation-subfield-design-for-eht-trigger-frame.pptx)**, “RU Allocation Subfield Design 4 EHT Trigger Frame”, Myeongjin Kim**

**Summary:** The authors propose to modify the RU allocation subfield to indicate the supported bandwidths.

**Discussion:**

C: What happens when the MRU’s becomes larger than 80 MHz? Can you get issues like reversed primary/secondary channels? Can you handle this?  
A: Yes.

1. **AoB:** Next call we will continue with trigger based contributions.
2. **Recess at 20:56**.